

Claims

- [c1] 1. A solder paste printing method comprising:
a first process for mounting a mask having apertures corresponding to land portions of a printed circuit board, on said printed circuit board at a predetermined position thereof in a state where it is placed in position;
a second process for mounting a solder paste containing therein as a solder material a tin-zinc (Sn-Zn) system solder on said mask and for permitting said solder paste to make rolling from one end of said mask toward the opposite end thereof by means of a squeegee, while maintaining moisture contained in the atmosphere surrounding said solder paste at a value equal to or less than a predetermined value, wherein said squeegee urges said solder paste to make rolling, to thereby fill said solder paste into said apertures; and
a third process for separating said mask away from said printed circuit board.
- [c2] 2. The solder paste printing method according to claim 1, wherein said moisture is equal to or less than 10 g/m^3 .
- [c3] 3. The solder paste printing method according to claim 2, wherein said atmosphere mainly comprises a nitrogen gas (N_2).
- [c4] 4. A solder paste printing apparatus comprising:
a mask having apertures corresponding to land portions of a printed circuit board;
a squeegee urging a solder paste containing therein as a solder material a tin-zinc (Sn-Zn) system solder and mounted on said mask, which is placed in position at a predetermined position on said printed circuit board to make rolling from one end of said mask toward the opposite end thereof; and
a moisture regulating means for maintaining moisture contained in the atmosphere surrounding said solder paste at a value equal to or less than a predetermined value.
- [c5] 5. The solder paste printing apparatus according to claim 4, wherein said moisture is equal to or less than 10 g/m^3 .
- [c6] 6. The solder paste printing apparatus according to claim 5, wherein said

atmosphere mainly comprises a nitrogen gas (N_2).

[c7]

Author	Year	Country	Sample Size	Age Range	Gender	Study Type	Findings
Alvares	2003	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2004	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2005	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2006	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2007	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2008	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2009	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2010	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2011	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2012	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2013	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2014	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2015	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2016	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2017	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2018	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2019	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety
Alvares	2020	Brazil	100	18-25	Male	Qualitative	High levels of stress and anxiety